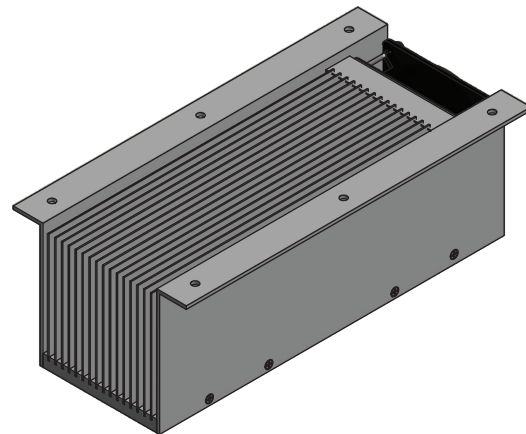
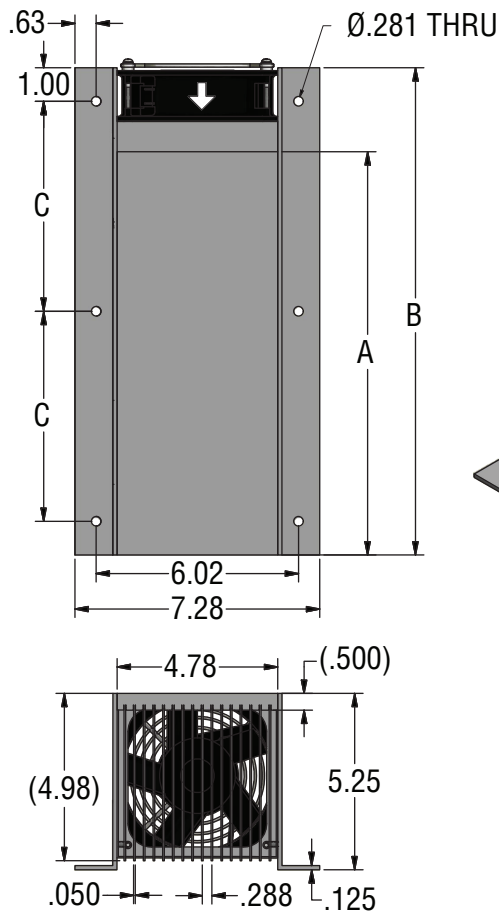


### FORCED CONVECTION – SINGLE FAN MODELS

Increased thermal performance over natural convection Bonded Fin Heat Sinks. Ideal for applications where high thermal density semiconductors, such as Power MOSFETs and IGBTs, are used. Models available fully equipped with a ball-bearing fan. **Custom designs are available upon request.**



### FORCED AIR CONVECTION - SINGLE FAN MODELS

MODEL #	CH5115F	CH5116F
Dimension A	7.00"	11.81"
Dimension B	9.50"	14.50"
Dimension C	3.75"	6.25"
Thermal Resistance	0.08°C/W	0.06°C/W

Thermal performances based on 100 CFM fan. Mounting pattern shown fits standard "muffin" fans.